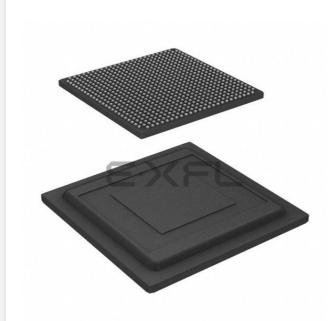
E·XFL

Intel - 5AGXMA7D4F27C5N Datasheet



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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Det	ai	ls

Details	
Product Status	Obsolete
Number of LABs/CLBs	11460
Number of Logic Elements/Cells	242000
Total RAM Bits	15470592
Number of I/O	336
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA, FCBGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxma7d4f27c5n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



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Arria V GX, GT, SX, and ST Device Datasheet



This datasheet describes the electrical characteristics, switching characteristics, configuration specifications, and I/O timing for Arria® V devices.

Arria V devices are offered in commercial and industrial grades. Commercial devices are offered in -C4 (fastest), -C5, and -C6 speed grades. Industrial grade devices are offered in the -I3 and -I5 speed grades.

Related Information

Arria V Device Overview

Provides more information about the densities and packages of devices in the Arria V family.

Electrical Characteristics

The following sections describe the operating conditions and power consumption of Arria V devices.

Operating Conditions

Arria V devices are rated according to a set of defined parameters. To maintain the highest possible performance and reliability of the Arria V devices, you must consider the operating requirements described in this section.

Absolute Maximum Ratings

This section defines the maximum operating conditions for Arria V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms.

The functional operation of the device is not implied for these conditions.

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I/O Pin Leakage Current

Table 1-6: I/O Pin Leakage Current for Arria V Devices

Symbol	Description	Condition	Min	Тур	Max	Unit
II	Input pin	$V_{I} = 0 V$ to $V_{CCIOMAX}$	-30	—	30	μΑ
I _{OZ}	Tri-stated I/O pin	$V_{O} = 0 V$ to $V_{CCIOMAX}$	-30		30	μΑ

Bus Hold Specifications

Table 1-7: Bus Hold Parameters for Arria V Devices

The bus-hold trip points are based on calculated input voltages from the JEDEC standard.

				V _{CCIO} (V)											
Parameter	Symbol	Condition	1	.2	1	.5	1	.8	2	.5	3	.0	3.	.3	Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus-hold, low, sustaining current	I _{SUSL}	V _{IN} > V _{IL} (max)	8		12		30		50		70		70	_	μΑ
Bus-hold, high, sustaining current	I _{SUSH}	V _{IN} < V _{IH} (min)	-8		-12		-30		-50		-70		-70	_	μΑ
Bus-hold, low, overdrive current	I _{ODL}	$\begin{array}{c} 0 \ V < V_{IN} \\ < V_{CCIO} \end{array}$	_	125		175	_	200		300	_	500		500	μΑ
Bus-hold, high, overdrive current	I _{ODH}	0 V <v<sub>IN <v<sub>CCIO</v<sub></v<sub>	_	-125		-175		-200	_	-300		-500		-500	μΑ

Arria V GX, GT, SX, and ST Device Datasheet

Altera Corporation



Figure 1-1: Equation for OCT Variation Without Recalibration

$$R_{OCT} = R_{SCAL} \left(1 + \left(\frac{dR}{dT} \times \Delta T \right) \pm \left(\frac{dR}{dV} \times \Delta V \right) \right)$$

The definitions for the equation are as follows:

- The R_{OCT} value calculated shows the range of OCT resistance with the variation of temperature and V_{CCIO}.
- R_{SCAL} is the OCT resistance value at power-up.
- ΔT is the variation of temperature with respect to the temperature at power up.
- ΔV is the variation of voltage with respect to the V_{CCIO} at power up.
- dR/dT is the percentage change of R_{SCAL} with temperature.
- dR/dV is the percentage change of R_{SCAL} with voltage.

OCT Variation after Power-Up Calibration

Table 1-10: OCT Variation after Power-Up Calibration for Arria V Devices

This table lists OCT variation with temperature and voltage after power-up calibration. The OCT variation is valid for a V_{CCIO} range of $\pm 5\%$ and a temperature range of 0°C to 85°C.

Symbol	Description	V _{CCIO} (V)	Value	Unit
		3.0	0.100	
	OCT variation with voltage without recalibration	2.5	0.100	
		1.8	0.100	
dR/dV		1.5	0.100	%/mV
		1.35	0.150	
		1.25	0.150	
		1.2	0.150	



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I/O Standard Specifications

Tables in this section list the input voltage (V_{IH} and V_{IL}), output voltage (V_{OH} and V_{OL}), and current drive characteristics (I_{OH} and I_{OL}) for various I/O standards supported by Arria V devices.

You must perform timing closure analysis to determine the maximum achievable frequency for general purpose I/O standards.

Single-Ended I/O Standards

I/O Standard		V _{CCIO} (V)			V _{IL} (V)	V _{IH}	(V)	V _{OL} (V)	V _{OH} (V)	I _{OL} ⁽¹³⁾	I _{OH} ⁽¹³⁾ (mA)
I/O Stanuaru	Min	Тур	Max	Min	Мах	Min	Мах	Мах	Min	(mA)	IOH, (IIIA)
3.3-V LVTTL	3.135	3.3	3.465	-0.3	0.8	1.7	3.6	0.45	2.4	4	-4
3.3-V LVCMOS	3.135	3.3	3.465	-0.3	0.8	1.7	3.6	0.2	V _{CCIO} – 0.2	2	-2
3.0-V LVTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
3.0-V LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	V _{CCIO} – 0.2	0.1	-0.1
3.0-V PCI	2.85	3	3.15	_	$0.3 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	1.5	-0.5
3.0-V PCI-X	2.85	3	3.15		$0.35 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	1.5	-0.5
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	0.45	V _{CCIO} – 0.45	2	-2
1.5 V	1.425	1.5	1.575	-0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	2	-2
1.2 V	1.14	1.2	1.26	-0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	2	-2

Table 1-14: Single-Ended I/O Standards for Arria V Devices

(13) To meet the I_{OL} and I_{OH} specifications, you must set the current strength settings accordingly. For example, to meet the 3.3-V LVTTL specification (4 mA), you should set the current strength settings to 4 mA. Setting at lower current strength may not meet the I_{OL} and I_{OH} specifications in the datasheet.



I/O Standard	V _{CCIO} (V)			V _{ID} (mV) ⁽¹⁶⁾		V _{ICM(DC)} (V)			V _{OD} (V) ⁽¹⁷⁾			V _{OCM} (V) ⁽¹⁷⁾⁽¹⁸⁾			
I/O Standard	Min	Тур	Мах	Min	Condition	Мах	Min	Condition	Мах	Min	Тур	Max	Min	Тур	Max
PCML	Transmitter, receiver, and input reference clock pins of high-speed transceivers use the PCML I/O standard. For transmitter, reference clock I/O pin specifications, refer to Transceiver Specifications for Arria V GX and SX Devices and Transceiver S for Arria V GT and ST Devices tables.														
2.5 V	2.375	2.5	2.625	100	V _{CM} =	$ \begin{array}{c c} - & 0.05 & D_{MAX} \leq & 1.80 \\ \hline 1.25 \text{ Gbps} & & 0.247 \end{array} $		0.6	1.125	1.25	1.375				
LVDS ⁽¹⁹⁾	2.375	2.3	2.023	100	1.25 V		1.05	D _{MAX} > 1.25 Gbps	_{IAX} > 1.55		0.0	1.125	1.23	1.575	
RSDS (HIO) ⁽²⁰⁾	2.375	2.5	2.625	100	V _{CM} = 1.25 V		0.25		1.45	0.1	0.2	0.6	0.5	1.2	1.4
Mini-LVDS (HIO) ⁽²¹⁾	2.375	2.5	2.625	200		600	0.300		1.425	0.25	_	0.6	1	1.2	1.4
LVPECL ⁽²²⁾				300			0.60	D _{MAX} ≤ 700 Mbps	1.80						
		_		500			1.00	D _{MAX} > 700 Mbps	1.60		_				

Related Information

- Transceiver Specifications for Arria V GX and SX Devices on page 1-23 Provides the specifications for transmitter, receiver, and reference clock I/O pin.
- $^{(16)}$ The minimum V_{ID} value is applicable over the entire common mode range, V_{CM}.
- ⁽¹⁷⁾ $R_{\rm L}$ range: $90 \le R_{\rm L} \le 110 \ \Omega$.
- ⁽¹⁸⁾ This applies to default pre-emphasis setting only.
- ⁽¹⁹⁾ For optimized LVDS receiver performance, the receiver voltage input range must be within 1.0 V to 1.6 V for data rates above 1.25 Gbps and 0 V to 1.85 V for data rates below 1.25 Gbps.
- ⁽²⁰⁾ For optimized RSDS receiver performance, the receiver voltage input range must be within 0.25 V to 1.45 V.
- ⁽²¹⁾ For optimized Mini-LVDS receiver performance, the receiver voltage input range must be within 0.3 V to 1.425 V.
- ⁽²²⁾ For optimized LVPECL receiver performance, the receiver voltage input range must be within 0.85 V to 1.75 V for data rates above 700 Mbps and 0.45 V to 1.95 V for data rates below 700 Mbps.



Symbol	V _{OD} Setting ⁽⁵⁸⁾	V _{OD} Value (mV)	V _{OD} Setting ⁽⁵⁸⁾	V _{OD} Value (mV)
	25	500	53	1060
	26	520	54	1080
	27	540	55	1100
	28	560	56	1120
	29	580	57	1140
	30	600	58	1160
	31	620	59	1180
	32	640	60	1200
	33	660		

Transmitter Pre-Emphasis Levels

The following table lists the simulation data on the transmitter pre-emphasis levels in dB for the first post tap under the following conditions:

- Low-frequency data pattern—five 1s and five 0s
- Data rate—2.5 Gbps

The levels listed are a representation of possible pre-emphasis levels under the specified conditions only and the pre-emphasis levels may change with data pattern and data rate.

Arria V devices only support 1st post tap pre-emphasis with the following conditions:

- The 1st post tap pre-emphasis settings must satisfy $|B| + |C| \le 60$ where $|B| = V_{OD}$ setting with termination value, $R_{TERM} = 100 \Omega$ and |C| = 1st post tap pre-emphasis setting.
- |B| |C| > 5 for data rates < 5 Gbps and |B| |C| > 8.25 for data rates > 5 Gbps.
- $(V_{MAX}/V_{MIN} 1)\% < 600\%$, where $V_{MAX} = |B| + |C|$ and $V_{MIN} = |B| |C|$.

Exception for PCIe Gen2 design: V_{OD} setting = 43 and pre-emphasis setting = 19 are allowed for PCIe Gen2 design with transmit de-emphasis – 6dB setting (pipe_txdeemp = 1'b0) using Altera PCIe Hard IP and PIPE IP cores.



⁽⁵⁸⁾ Convert these values to their binary equivalent form if you are using the dynamic reconfiguration mode for PMA analog controls.

Protocol	Sub-protocol	Data Rate (Mbps)
	SONET 155	155.52
SONET	SONET 622	622.08
	SONET 2488	2,488.32
	GPON 155	155.52
Gigabit-capable passive optical network (GPON)	GPON 622	622.08
Orgabil-Capable passive optical network (Or ON)	GPON 1244	1,244.16
	GPON 2488	2,488.32
QSGMII	QSGMII 5000	5,000

Core Performance Specifications

Clock Tree Specifications

Table 1-35: Clock Tree Specifications for Arria V Devices

Parameter		Performance	Unit	
	–I3, –C4	–I5, –C5	-C6	Onic
Global clock and Regional clock	625	625	525	MHz
Peripheral clock	450	400	350	MHz

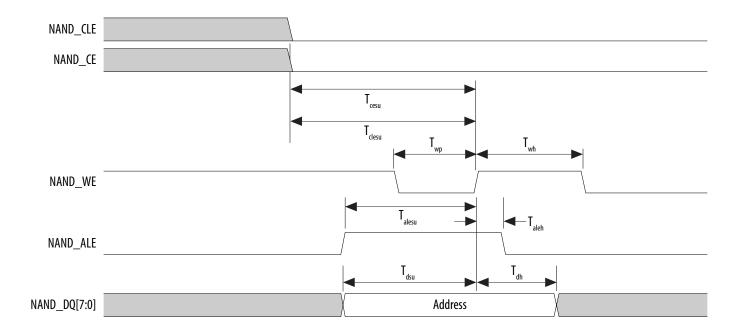
PLL Specifications

Table 1-36: PLL Specifications for Arria V Devices

This table lists the Arria V PLL block specifications. Arria V PLL block does not include HPS PLL.



Figure 1-18: NAND Address Latch Timing Diagram







			Active Seria	 (108)	Fast Passive Parallel ⁽¹⁰⁹⁾				
Variant	Member Code	Width	DCLK (MHz)	Minimum Configura- tion Time (ms)	Width	DCLK (MHz)	Minimum Configuration Time (ms)		
	A1	4	100	178	16	125	36		
	A3	4	100	178	16	125	36		
	A5	4	100	255	16	125	51		
Arria V GX	A7	4	100	255	16	125	51		
Anna v GA	B1	4	100	344	16	125	69		
	B3	4	100	344	16	125	69		
	B5	4	100	465	16	125	93		
	B7	4	100	465	16	125	93		
	C3	4	100	178	16	125	36		
Arria V GT	C7	4	100	255	16	125	51		
Allia v Gi	D3	4	100	344	16	125	69		
	D7	4	100	465	16	125	93		
Arria V SX	В3	4	100	465	16	125	93		
Allia V SA	B5	4	100	465	16	125	93		
Arria V ST	D3	4	100	465	16	125	93		
Alla v SI	D5	4	100	465	16	125	93		

Related Information Configuration Files on page 1-83

(108) DCLK frequency of 100 MHz using external CLKUSR.
 (109) Maximum FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

1-96 Document Revision History

Date	Version	Changes
June 2015	2015.06.16	• Added the supported data rates for the following output standards using true LVDS output buffer types in the High-Speed I/O Specifications for Arria V Devices table:
		True RSDS output standard: data rates of up to 360 Mbps
		True mini-LVDS output standard: data rates of up to 400 Mbps
		 Added note in the condition for Transmitter—Emulated Differential I/O Standards f_{HSDR} data rate parameter in the High-Speed I/O Specifications for Arria V Devices table. Note: When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.
		Changed Queued Serial Peripheral Interface (QSPI) to Quad Serial Peripheral Interface (SPI) Flash.
		Updated T _h location in I ² C Timing Diagram.
		Updared T _{wp} location in NAND Address Latch Timing Diagram.
		 Corrected the unit for t_{DH} from ns to s in FPP Timing Parameters When DCLK-to-DATA[] Ratio is >1 for Arria V Devices table.
		• Updated the maximum value for t _{CO} from 4 ns to 2 ns in AS Timing Parameters for AS ×1 and ×4 Configurations in Arria V Devices table.
		• Moved the following timing diagrams to the Configuration, Design Security, and Remote System Upgrades in Arria V Devices chapter.
		FPP Configuration Timing Waveform When DCLK-to-DATA[] Ratio is 1
		• FPP Configuration Timing Waveform When DCLK-to-DATA[] Ratio is >1
		AS Configuration Timing Waveform
		PS Configuration Timing Waveform





This document covers the electrical and switching characteristics for Arria V GZ devices. Electrical characteristics include operating conditions and power consumption. Switching characteristics include transceiver specifications, core, and periphery performance. This document also describes I/O timing, including programmable I/O element (IOE) delay and programmable output buffer delay.

Related Information

Arria V Device Overview

For information regarding the densities and packages of devices in the Arria V GZ family.

Electrical Characteristics

Operating Conditions

When you use Arria V GZ devices, they are rated according to a set of defined parameters. To maintain the highest possible performance and reliability of Arria V GZ devices, you must consider the operating requirements described in this datasheet.

Arria V GZ devices are offered in commercial and industrial temperature grades.

Commercial devices are offered in -3 (fastest) and -4 core speed grades. Industrial devices are offered in -3L and -4 core speed grades. Arria V GZ devices are offered in -2 and -3 transceiver speed grades.

Table 2-1: Commercial and Industrial Speed Grade Offering for Arria V GZ Devices

C = Commercial temperature grade; I = Industrial temperature grade.

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2-4 Recommended Operating Conditions

The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle.

For example, a signal that overshoots to 3.95 V can be at 3.95 V for only $\sim 21\%$ over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~ 2 years.

Table 2-4: Maximum Allowed Overshoot During Transitions for Arria V GZ Devices
--

Symbol	Description	Condition (V)	Overshoot Duration as $\% @ T_J = 100^{\circ}C$	Unit
		3.8	100	%
		3.85	64	%
		3.9	36	%
		3.95	21	%
Vi (AC)	AC input voltage	4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

Recommended Operating Conditions

Table 2-5: Recommended Operating Conditions for Arria V GZ Devices

Power supply ramps must all be strictly monotonic, without plateaus.

Symbol	Description	Condition	Minimum ⁽¹¹⁴⁾	Typical	Maximum ⁽¹¹⁴⁾	Unit
V _{CC}	Core voltage and periphery circuitry power supply (115)	_	0.82	0.85	0.88	V

⁽¹¹⁴⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.





⁽¹¹⁵⁾ The V_{CC} core supply must be set to 0.9 V if the Partial Reconfiguration (PR) feature is used.

I/O Standard		V _{CCIO} (V)			V _{REF} (V)			V _T	_T (V)
	Min	Тур	Max	Min	Тур	Max	Min	Тур	Мах
SSTL-135 Class I, II	1.283	1.35	1.418	$0.49 \times V_{CCIO}$	$0.5 imes V_{ m CCIO}$	$0.51 imes V_{ m CCIO}$	$0.49 \times V_{ m CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
SSTL-125 Class I, II	1.19	1.25	1.26	$0.49 \times V_{CCIO}$	$0.5 \times V_{ m CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{ m CCIO}$	0.5 × VCCIO	$0.51 \times V_{CCIO}$
SSTL-12 Class I, II	1.14	1.20	1.26	$0.49 \times V_{CCIO}$	$0.5 imes V_{ m CCIO}$	$0.51 \times V_{ m CCIO}$	$0.49 \times V_{ m CCIO}$	0.5 × VCCIO	$0.51 \times V_{CCIO}$
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	_	V _{CCIO} /2	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9		V _{CCIO} /2	_
HSTL-12 Class I, II	1.14	1.2	1.26	$0.47 \times V_{CCIO}$	$0.5 imes V_{ m CCIO}$	$0.53 \times V_{ m CCIO}$	_	V _{CCIO} /2	_
HSUL-12	1.14	1.2	1.3	$0.49 \times V_{CCIO}$	$0.5 imes V_{ m CCIO}$	0.51 × V _{CCIO}	_	—	_

Table 2-18: Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Arria V GZ Devices

I/O Standard	I/O Standard) V _{IH(DC)} (V)			V _{IH(AC)} (V)	V _{OL} (V)	V _{OH} (V)	l _{ol} (mA)	l _{oh} (mA)
	Min	Max	Min	Max	Мах	Min	Max	Min	י _{סן} (וויה)	ion (iii) (
SSTL-2 Class I	-0.3	V _{REF} – 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} – 0.31	V _{REF} + 0.31	V _{TT} – 0.608	V _{TT} + 0.608	8.1	-8.1
SSTL-2 Class II	-0.3	V _{REF} – 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} – 0.31	V _{REF} + 0.31	V _{TT} – 0.81	V _{TT} + 0.81	16.2	-16.2
SSTL-18 Class I	-0.3	V _{REF} – 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} – 0.25	V _{REF} + 0.25	V _{TT} - 0.603	V _{TT} + 0.603	6.7	-6.7



I/O Standard	V _{CCIO} (V)			V _{DIF(DC)} (V)			$V_{X(AC)}(V)$			_{1(DC)} (V	V _{DIF(AC)} (V)		
	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V _{CCIO} + 0.3		$0.5 \times V_{CCIO}$		$0.4 \times V_{\rm CCIO}$	0.5 × V _{CC} IO	$0.6 \times V_{CCIO}$	0.3	V _{CCIO} + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	$0.5 \times V_{\rm CCIO} - 0.12$	$0.5 \times V_{CCIO}$	$0.5 \times V_{CCIO} + 0.12$	$0.4 \times V_{ m CCIO}$	0.5 × V _{CC} IO	$0.6 \times V_{CCIO}$	0.44	0.44

Table 2-21: Differential I/O Standard Specifications for Arria V GZ Devices

1/O Standard	I/O Standard			V _{ID} (mV) ⁽¹²⁹⁾				V _{ICM(DC)} (V)			V _{OD} (V) ⁽¹³⁰⁾			V _{OCM} (V) ⁽¹³⁰⁾		
	Min	Тур	Max	Min	Condition	Max	Min	Condition	Max	Min	Тур	Max	Min	Тур	Max	
PCML	PCML Transmitter, receiver, and input reference clock pins of the high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to the "Transceiver Performance Specifications" section.															
2.5 V LVDS	2.375	2.5	2.625	100	V _{CM} =		0.05	D _{MAX} ≤ 700 Mbps	1.8	0.247		0.6	1.125	1.25	1.375	
(131)	2.373	2.3	2.025	100	1.25 V	_	1.05	D _{MAX} > 700 Mbps	1.55	0.247	—	0.6	1.125	1.25	1.375	
BLVDS (132)	2.375	2.5	2.625	100												

⁽¹²⁸⁾ Differential inputs are powered by VCCPD which requires 2.5 V.



⁽¹²⁹⁾ The minimum VID value is applicable over the entire common mode range, VCM.

⁽¹³⁰⁾ RL range: $90 \le \text{RL} \le 110 \Omega$.

⁽¹³¹⁾ For optimized LVDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.

 $^{^{(132)}}$ There are no fixed V_{ICM}, V_{OD}, and V_{OCM} specifications for BLVDS. They depend on the system topology.

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Symbol/Description	Conditions	Trans	ceiver Spee	d Grade 2	Transc	Unit		
Symbol/Description	Conditions	Min	Тур	Мах	Min	Тур	Max	
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) before device configuration	_	_	_	1.6	_	_	1.6	V
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) after	$V_{CCR_GXB} = 1.0 V$ $(V_{ICM} = 0.75 V)$	_	_	1.8	_		1.8	V
device configuration ⁽¹⁴⁶⁾	$V_{CCR_GXB} = 0.85 V$ $(V_{ICM} = 0.6 V)$		_	2.4	_	_	2.4	V
Minimum differential eye opening at receiver serial input pins ⁽¹⁴⁷⁾⁽¹⁴⁸⁾	_	85	_	_	85	_		mV
	85– Ω setting		85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-chip termination	100– Ω setting		100 ± 30%		_	100 ± 30%		Ω
resistors	120– Ω setting	—	120 ± 30%		—	120 ± 30%		Ω
	150– Ω setting	—	150 ± 30%		_	150 ± 30%		Ω



⁽¹⁴⁶⁾ The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin - V_{ICM}).

⁽¹⁴⁷⁾ The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.

⁽¹⁴⁸⁾ Minimum eye opening of 85 mV is only for the unstressed input eye condition.

2-28	Transmitter
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Symbol/Description	Conditions	Trans	ceiver Spee	d Grade 2	Transc	eiver Spee	ed Grade 3	Unit
Symbol/Description	Conditions	Min	Тур	Мах	Min	Тур	Мах	Onic
	85- Ω setting	_	85 ± 20%	_		85 ± 20%	_	Ω
Differential on-chip termination	100-Ω setting	—	100 ± 20%	_		100 ± 20%		Ω
resistors	120-Ω setting	_	120 ± 20%			120 ± 20%		Ω
	150-Ω setting	_	150 ± 20%	_		150 ± 20%		Ω
V _{OCM} (AC coupled)	0.65-V setting	_	650			650		mV
V _{OCM} (DC coupled)	_		650			650		mV
Intra-differential pair skew	Tx V _{CM} = 0.5 V and slew rate of 15 ps	_	_	15	_	_	15	ps
Intra-transceiver block transmitter channel-to-channel skew	x6 PMA bonded mode	—		120		_	120	ps
Inter-transceiver block transmitter channel-to-channel skew	xN PMA bonded mode	—	—	500	_	_	500	ps

Related Information

Arria V Device Overview

For more information about device ordering codes.



Symbol	Conditions		C3, I3L			C4, I4		Unit
Symbol	Conditions	Min	Тур	Мах	Min	Тур	Max	Onic
	SERDES factor $J = 3$ to 10 (192), (193), (194), (195), (196), (197)	150	_	1250	150		1050	Mbps
True Differential I/O Standards - f _{HSDRDPA}	SERDES factor $J \ge 4$ LVDS RX with DPA (193), (195), (196), (197)	150		1600	150		1250	Mbps
(data rate)	SERDES factor J = 2, uses DDR Registers	(198)	_	(199)	(198)	_	(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)		(199)	(198)		(199)	Mbps
	SERDES factor $J = 3$ to 10	(198)	—	(200)	(198)	_	(200)	Mbps
f _{HSDR} (data rate)	SERDES factor J = 2, uses DDR Registers	(198)	—	(199)	(198)		(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)	_	(199)	(198)	_	(199)	Mbps

 $^{(192)}$ The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design dependent and requires timing analysis.

⁽¹⁹³⁾ Arria V GZ RX LVDS will need DPA. For Arria V GZ TX LVDS, the receiver side component must have DPA.

⁽¹⁹⁴⁾ Arria V GZ LVDS serialization and de-serialization factor needs to be x4 and above.

⁽¹⁹⁵⁾ Requires package skew compensation with PCB trace length.

⁽¹⁹⁶⁾ Do not mix single-ended I/O buffer within LVDS I/O bank.

⁽¹⁹⁷⁾ Chip-to-chip communication only with a maximum load of 5 pF.

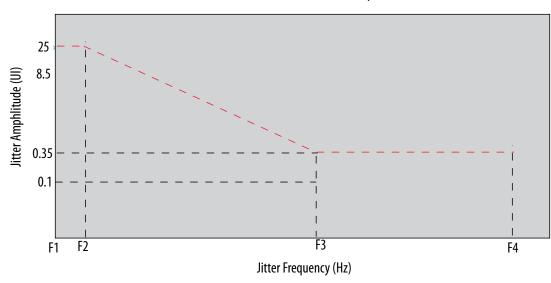
⁽¹⁹⁸⁾ The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.

⁽¹⁹⁹⁾ The maximum ideal data rate is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.

⁽²⁰⁰⁾ You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.



Figure 2-4: LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate ≥ 1.25 Gbps



LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification

Table 2-45: LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for a Data Rate ≥ 1.25 Gbps

Jitter Frequency (Hz)		Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350



Term	Definition
t _C	High-speed receiver and transmitter input and output clock period.
TCCS (channel-to- channel-skew)	The timing difference between the fastest and slowest output edges, including t _{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the Timing Diagram figure under SW in this table).
t _{DUTY}	High-speed I/O block—Duty cycle on the high-speed transmitter output clock.
t _{FALL}	Signal high-to-low transition time (80-20%)
t _{INCCJ}	Cycle-to-cycle jitter tolerance on the PLL clock input.
t _{OUTPJ_IO}	Period jitter on the general purpose I/O driven by a PLL.
t _{OUTPJ_DC}	Period jitter on the dedicated clock output driven by a PLL.
t _{RISE}	Signal low-to-high transition time (20-80%)
Timing Unit Interval (TUI)	The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = $1/(\text{receiver input clock frequency multiplication factor}) = t_C/w)$
V _{CM(DC)}	DC common mode input voltage.
V _{ICM}	Input common mode voltage—The common mode of the differential signal at the receiver.
V _{ID}	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
V _{DIF(AC)}	AC differential input voltage—Minimum AC input differential voltage required for switching.
V _{DIF(DC)}	DC differential input voltage— Minimum DC input differential voltage required for switching.
V _{IH}	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
V _{IH(AC)}	High-level AC input voltage
V _{IH(DC)}	High-level DC input voltage
V _{IL}	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
V _{IL(AC)}	Low-level AC input voltage
V _{IL(DC)}	Low-level DC input voltage

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